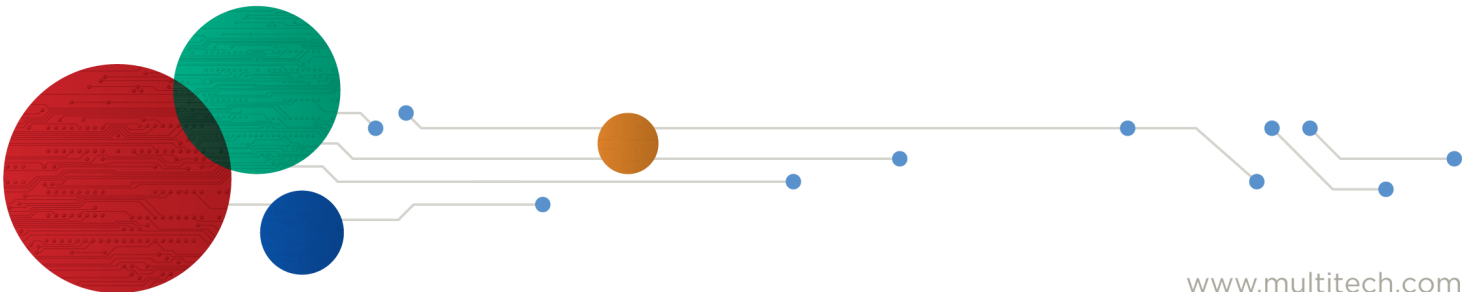


# Universal Developer Kit 2.0

## MTUDK-ST-Cell Developer Guide



## Universal Developer Kit 2.0 Developer Guide

Models: MTUDK-ST-Cell

Document Part Number: S000610 Rev. 2.7

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# Chapter 1 Developer Kit Introduction

## Overview

The MTUDK2-ST-Cell Universal Developer Kit supports development with cellular SocketModem, SocketModem MTQ (including SocketModem MTQN), and mDot devices. Use the developer board to streamline your development efforts and evaluate your products and applications. Easily plug in your communications device and use the developer kit for testing, programming and evaluation.

**Note:** Use this Developer Guide for developing with all SocketModem or SocketModem MTQ models. If developing with an mDot, use the mDot Developer Guide, which includes device and developer board information specific to mDots. Go to the mDot Developer Kit page at <http://www.multitech.com/models/94558010LF>.

**Warning:** Do not use an mDot and a SocketModem MTQ or Socketmodem on this board at the same time. Doing so may damage both devices.

## Features

- 5V-9V power input
- Selectable 3.3V or 5V on board power supply for mDot and SocketModem and 5V only for SocketModem MTQ models
- USB and serial interfaces
- USB port for mbed development environment
- Arduino shield socket

## Device Specific Documentation

Refer to the Device Guide for your SocketModem or SocketModem MTQ model for specifications, pin information, mechanical drawings, labeling, regulatory information, and other model specific details.

## MTUDK2-ST-CELL Developer Kit Contents

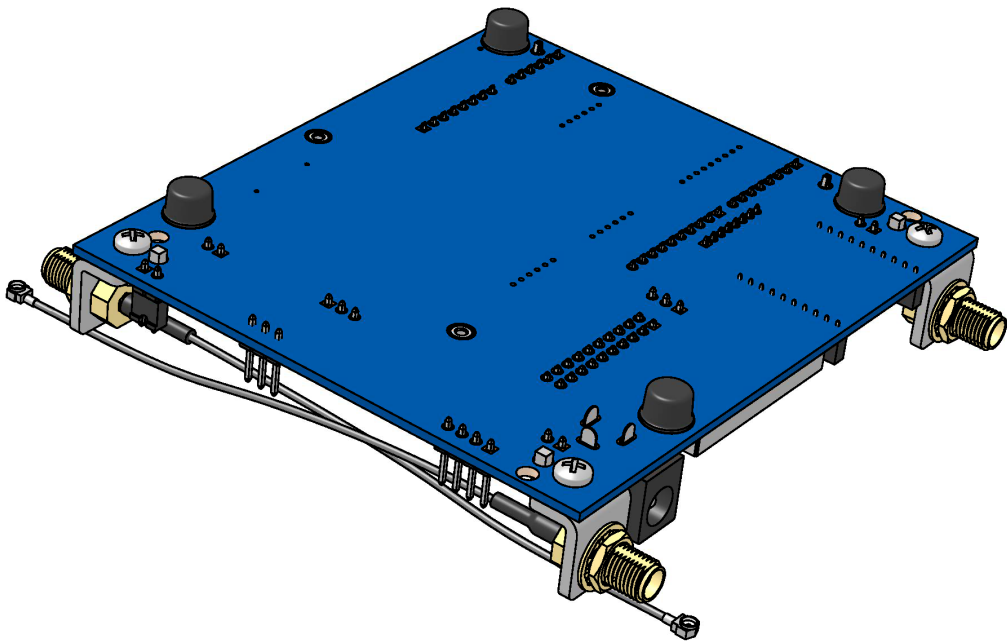
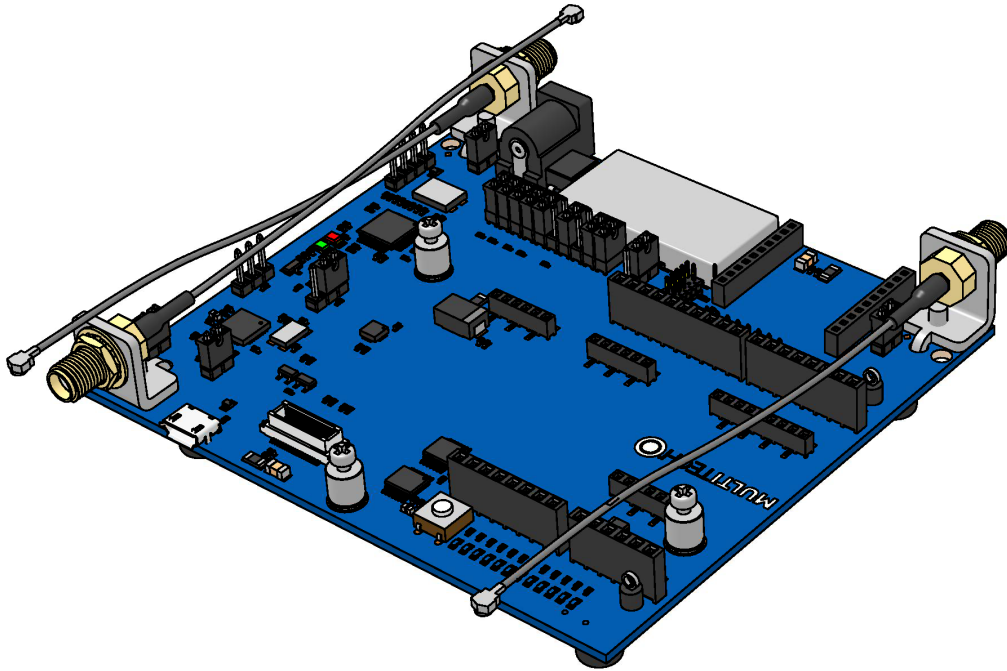
The MTUDK2-ST-CELL Developer Kit includes the following:

Developer Board	1 - MTUDK 2.0 Cell Developer Board
Power Supply	1 - 100-240V 9V-1.7A power supply with removable blades
	1 - NAM blade/plug,
	1 - EURO blade/plug
	1 - UK blade/plug
	1 - AU/NZ blade/plug
Cables	1 - Micro USB Cable
	3 - SMA-U.FL Antenna Cables (attached to developer board)
Antennas	1 - 3.3V magnetic GPS Antenna
	2 - 700-2600 MHz Antennas

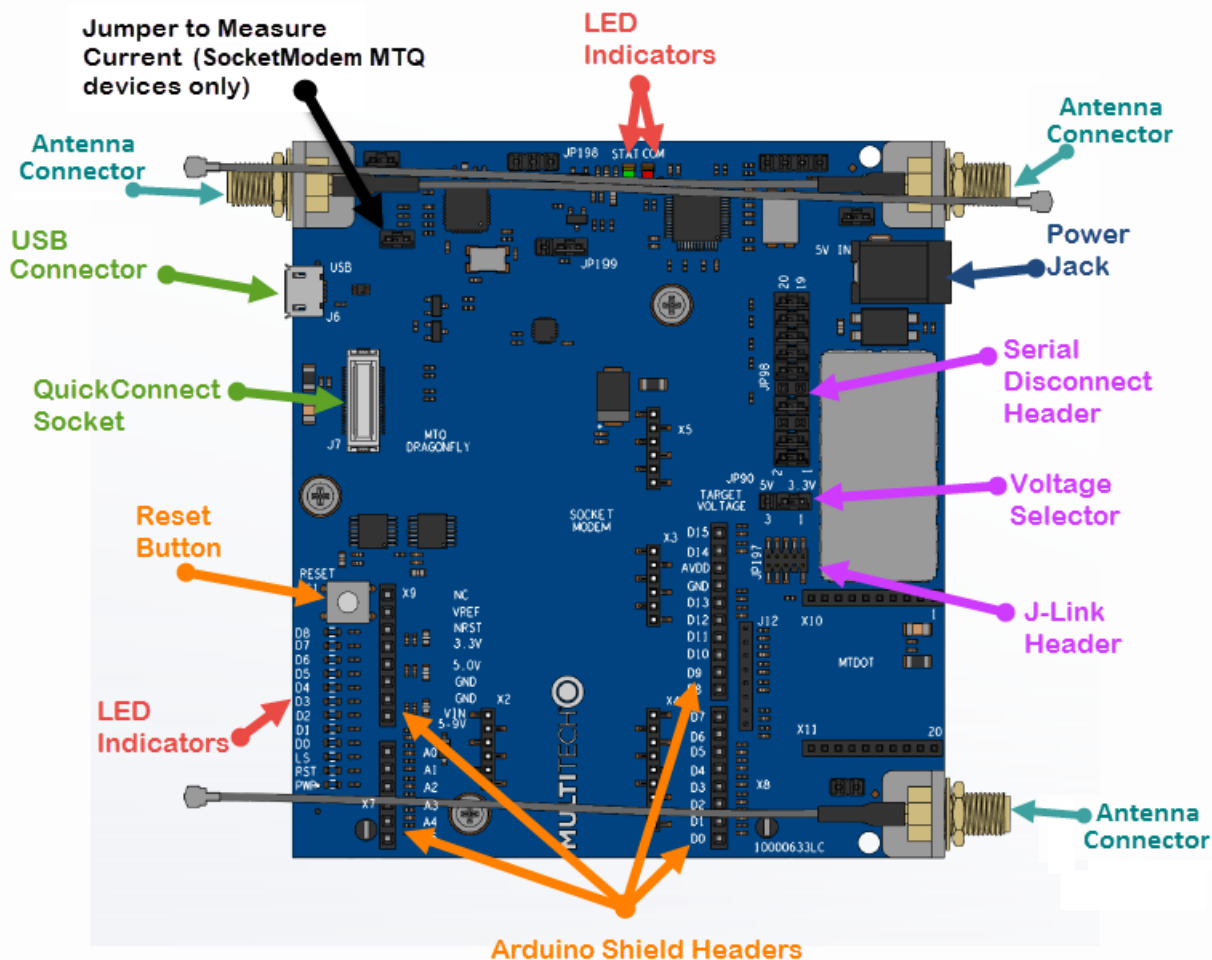
Customer Notices	Quick Start
Additional	One promotional screwdriver

## Chapter 2 Board Components

### Developer Board



## Developer Board Connectors



## Board Components

Label	Description
Voltage Selector	Selects between the on-board 3.3V or 5V regulator for powering a SocketModem, or mDot. Factory default operating voltage is 5V. (Note: Does not apply to SocketModem MTQ devices which use the QuickConnect Socket that is 5V only.)
J6	USB connection for mbed, serial, and SocketModem. For the SocketModem MTQ, use USB connector on the SocketModem MTQ. For information on connecting to and using mbed, refer to the device guide for your SocketModem MTQ model. (Not available for SocketModems.)
J7	QuickConnect Socket (for SocketModem MTQ devices).
JP98	Serial Disconnect Header.
JP197	J-Link Header.
S1	Reset Button. Use to reset the processor of the device attached to the board.



Label	Description
X2	SocketModem, USB Connector.
X3	SocketModem, GPIO (not connected).
X4	SocketModem Serial Connector.
X5	SocketModem Power Connector.
X6	Arduino Shield Connector.
X7	Arduino Shield Connector.
X8	Arduino Shield Connector.
X9	Arduino Shield Connector.

**CAUTION:** Take care when connecting or disconnecting USB cables to avoid detaching the connector from the board.

## LED Indicators

Label	LED	Location
STAT	LED1	Near JP198
COM	LED2	Near JP198
D7	LED3	Above the SMC-USB connector
D4	LED4	Above the SMC-USB connector
D5	LED5	Above the SMC-USB connector
D8	LED6	Above the SMC-USB connector
D6	LED7	Above the SMC-USB connector
D3	LED8	Above the SMC-USB connector
D0	LED9	Above the SMC-USB connector
D1	LED10	Above the SMC-USB connector
LS	LED11	Above the SMC-USB connector
RST	LED12	Above the SMC-USB connector
PWR	LED13	Above the SMC-USB connector
D2	LED14	Above the SMC-USB connector

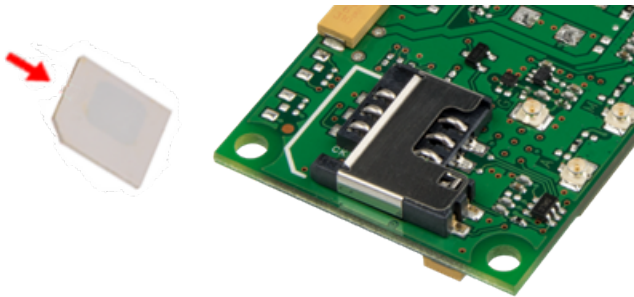
## Chapter 3 Installation and Operation

### Installing a SIM Card on a SocketModem Cell

**Note:** When using the SocketModem Cell with a developer board, mount the SocketModem Cell on the developer board before installing the SIM card.

To install the SIM Card:

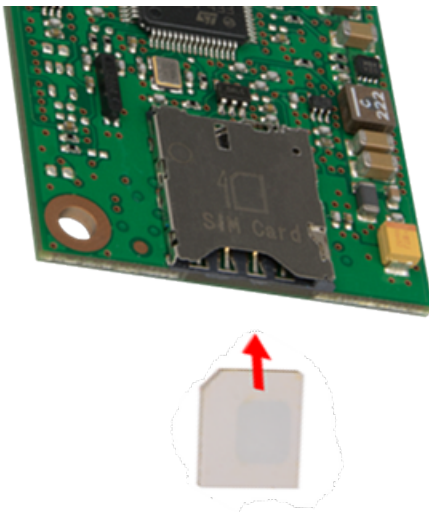
- With the contact side facing down, align the notched edge as outlined on the SocketModem Cell and slide the SIM card completely into the SIM holder.



### Installing a SIM Card on a SocketModem

When using the SocketModem with a developer board, install the SIM card before mounting the SocketModem on the developer board.

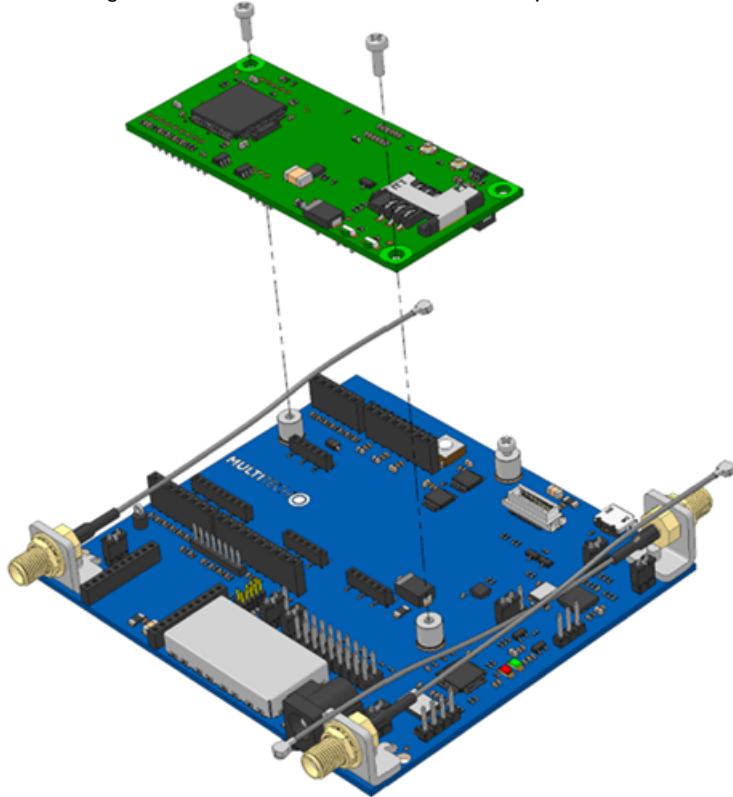
With the contact side facing down, align the notched edge as shown on the SocketModem's SIM holder and slide the SIM card completely into the SIM holder.



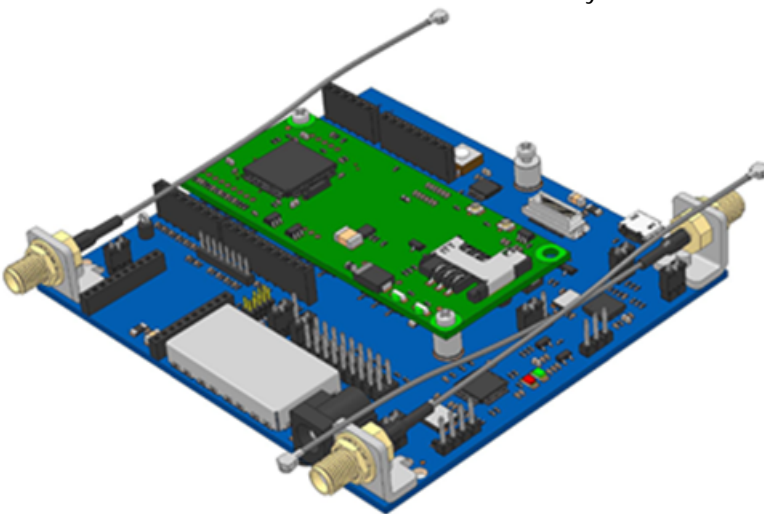
## Installing a SocketModem on the Developer Board

To install a SocketModem:

1. Remove the screws from the developer board.
2. Align the SocketModem on the developer board as shown.



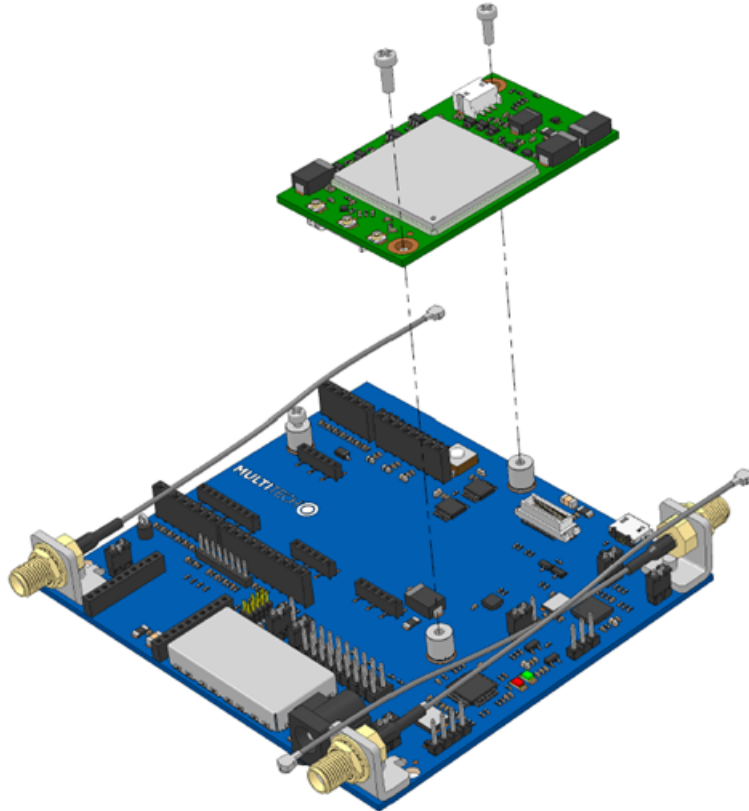
3. Secure the SocketModem with the screws you removed in Step 1.



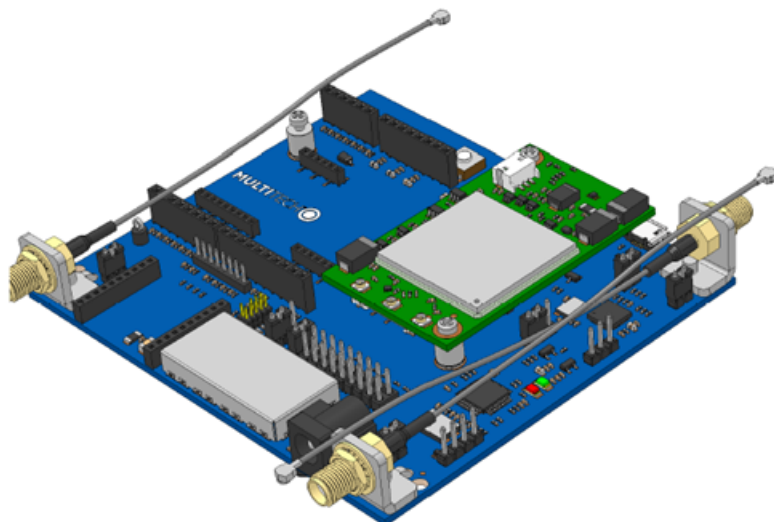
## Installing a SocketModem MTQ on the Developer Board

To install a SocketModem MTQ:

1. Remove the screws from the developer board.
2. Align the SocketModem MTQ on the developer board as shown.



3. Secure the SocketModem MTQ with the screws you removed in Step 1.

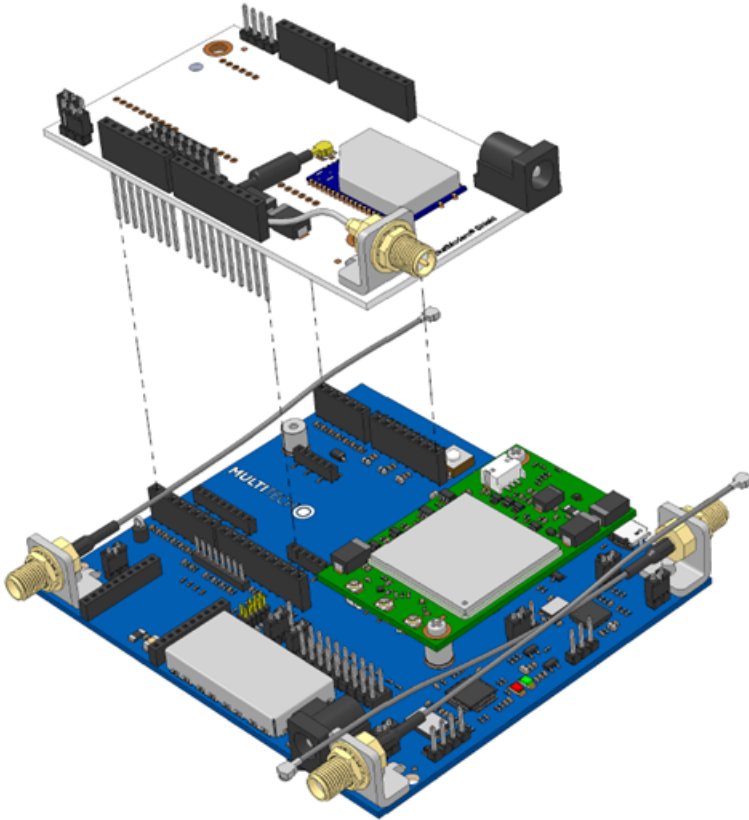


## Installing an Arduino Shield with a SocketModem MTQ

**Note:** When using an Arduino Shield with a SocketModem MTQ, install the SIM card in the SocketModem MTQ and then install the SocketModem MTQ on the developer board before installing the Arduino shield.

To use an Arduino Shield with a SocketModem MTQ

1. Disable the developer card's serial port.
2. Align the Arduino Shield on the developer board as shown. It will overlap the SocketModem MTQ.



## SocketModem MTQ Arduino Pins

Signals (MTQ-B01, MTQ-B02 Models)		Arduino Shield			Signals STM32F411RE processor (MTQ-B01 Models)
			D15	X5	D15 (PB8)
			D14		D14 (PB9)
			AVDD		NC
			GND		Ground
	X8	NC	D13	X5	D13 (PA5)
NC		VREF	D12		D12(PA6)
nReset, from pushbutton		nRST	D11		D11 (PB5)
NC		3.3V	D10		D10 (PC8)
5.0V		5.0V	D9		D9 (PB13)
Ground		GND	D8		D8 (PB1)
Ground		GND			
NC		VIN	D7	X7	D7 (PA8)
			D6		D6 (PA1)
A0 (PC2)	X6	A0	D5		D5 (PA9)
A1 (PC0)		A1	D4		D4 (PA7)
A2 (PC4)		A2	D3		D3 (PA0)
A3 (PB0)		A3	D2		D2 (PB15)
A4 (PC1)		A4	D1		D1 (PA2)
A5 (PC9)		A5	D0		D0 (PA3)

## SocketModem MTQN Arduino Pins

Signals (MTQN-B01, MTQN-B02 Models)		Arduino Shield			Signals STM32L471QG processor (MTQN-B01 Models)
			D15	X5	D15 (PB8)
			D14		D14 (PB9)
			AVDD		NC
			GND		Ground
	X8	NC	D13	X5	D13 (PG2)
NC		VREF	D12		D12(PG3)
nReset, from pushbutton		nRST	D11		D11 (PB5)
NC		3.3V	D10		D10 (PC8)
5.0V		5.0V	D9		D9 (PB10)
Ground		GND	D8		D8 (PB0)
Ground		GND			
NC		VIN	D7	X7	D7 (PG7)
			D6		D6 (PA1)
A0 (PC2)	X6	A0	D5		D5 (PA9)
A1 (PC13)		A1	D4		D4 (PA7)
A2 (PC4)		A2	D3		D3 (PA0)
A3 (PE6)		A3	D2		D2 (PB15)
A4 (PA6)		A4	D1		D1 (PA2)
A5 (PG8)		A5	D0		D0 (PA3)

## mDot Arduino Pins

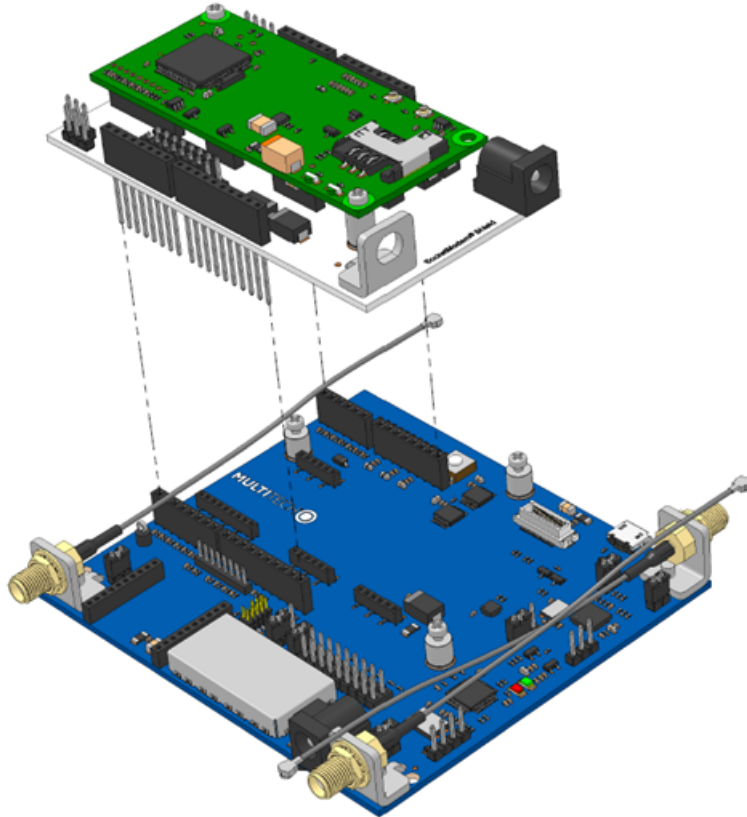
Signals (module pin) micro pin		Arduino Shield				Signals (module pin) micro pin	
					D15		PWM0/RSSI/I2CSCL (6) PA8
					D14		PWM1/I2CSDA (7) PC9
					AVDD		3.3V
					GND		Ground
			NC		D13	X6	AD2/DIO2/SCK (18) PA5
3.3V			VREF		D12		DO8/MISO (4) PA6
nReset, from pushbutton			nRST		D11		AD4/DIO4/MOSI (11) PA7
3.3V			3.3V		D10		AD3/DIO3/SNSS (17) PA4
5.0V	X9		5.0V		D9		no connect
Ground			GND		D8		no connect
Ground			GND				
5-9V input from J3			VIN		D7		nDTR/SleepRQ/DI8 (9) PA11
					D6		nRTS/AD6/DIO6 (16) PA1
AD0/DIO0 (20) PB1			A0		D5		no connect
AD1/DIO1 (19) PB0			A1		D4	X8	no connect
Associate/AD5/DIO5 (15) PC1	X7		A2		D3		nCTS/DIO7 (12) PA0
no connect			A3		D2		ON/nSleep (13) PC13
no connect			A4		D1		Dout (2) PA2
no connect			A5		D0		Din (3) PA3



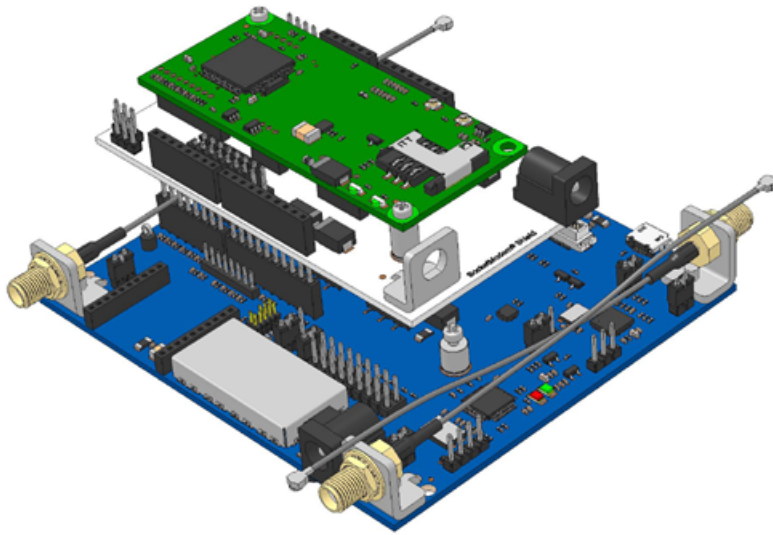
## Installing an Arduino Shield with a SocketModem

If using an Arduino Shield with a SocketModem:

1. Move jumpers for JP98 as follows:
  - Move Jumper 3-4 to Jumper 5-6
  - Move Jumper 7-8 to Jumper 9-10
2. Mount the MTSMC device on the Arduino shield as shown in the following image.



3. Connect the Arduino Shield to the developer board.



## Attaching Power Supply Blades

### Power Supply and Blades

If your device shipped with a power supply, attach the blades for your region.



Power Supply no  
blades



Power Supply with  
EU blade



Power Supply with US  
blade



Power Supply with  
GB blade

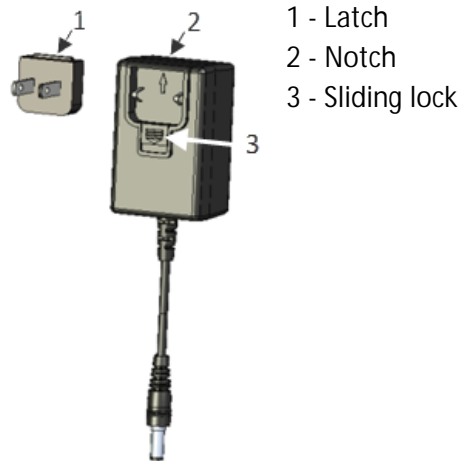


Power Supply with  
AU-NZ blade

### Attaching the Blades

To attach a power supply blade:

1. Remove the power supply cover (not shown). To do this, slide the lock down and hold it while you lift off the cover.
2. Insert the latch on the blade into the notch on the power supply.
3. Slide the lock down and hold it while you press the blade in place. Then, release it.



## SMA to U.FL Cables

The developer kit includes three 4.5" SMA to U.FL cables which are preinstalled on the developer board. Consult the mechanical drawings for your device to determine which antenna to connect to which U.FL connector on the device.



## Connecting an Antenna through the Developer Board Connectors

To connect an antenna to the device through the developer board:

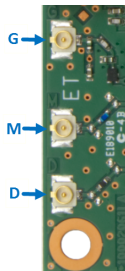
1. Determine which SMA connector you want to use for the antenna.
2. Finger tighten the antenna to the SMA connector.
3. Attach the U.FL connector from the cable to the connector on the device.

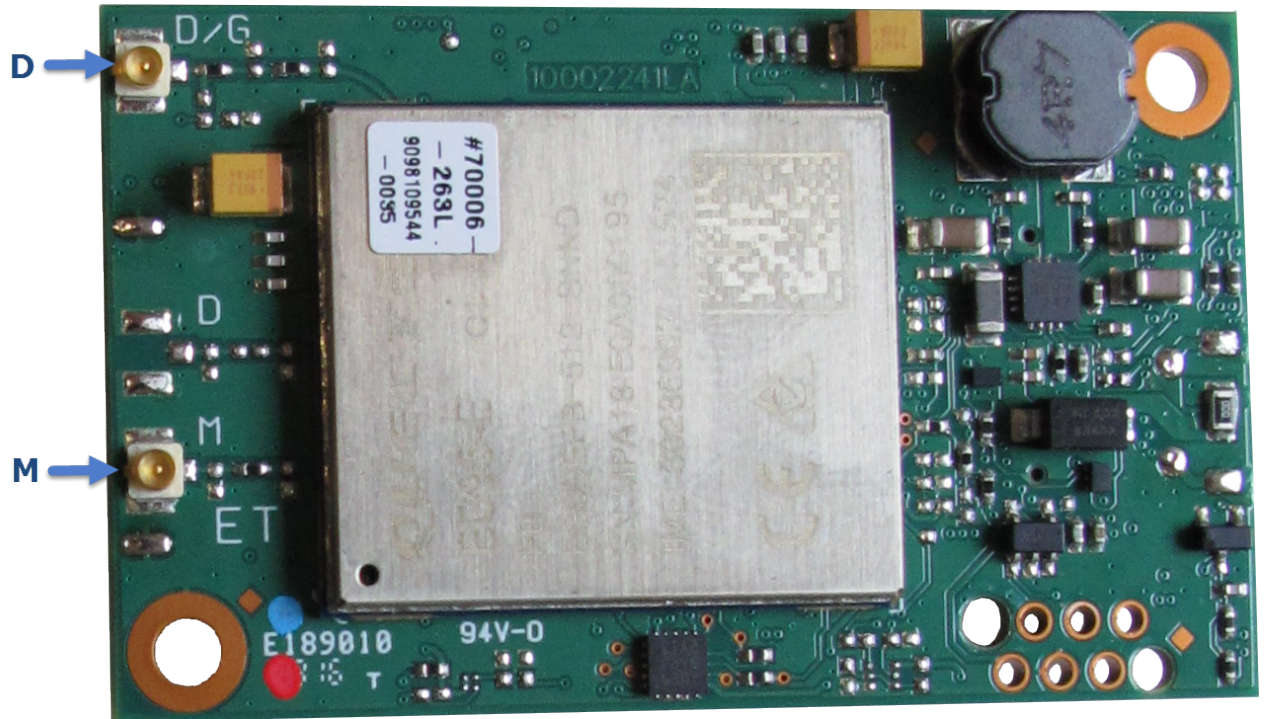


G = GNSS (may not apply to your device)

M = Main

D = Auxiliary/Diversity (may not apply to your device)

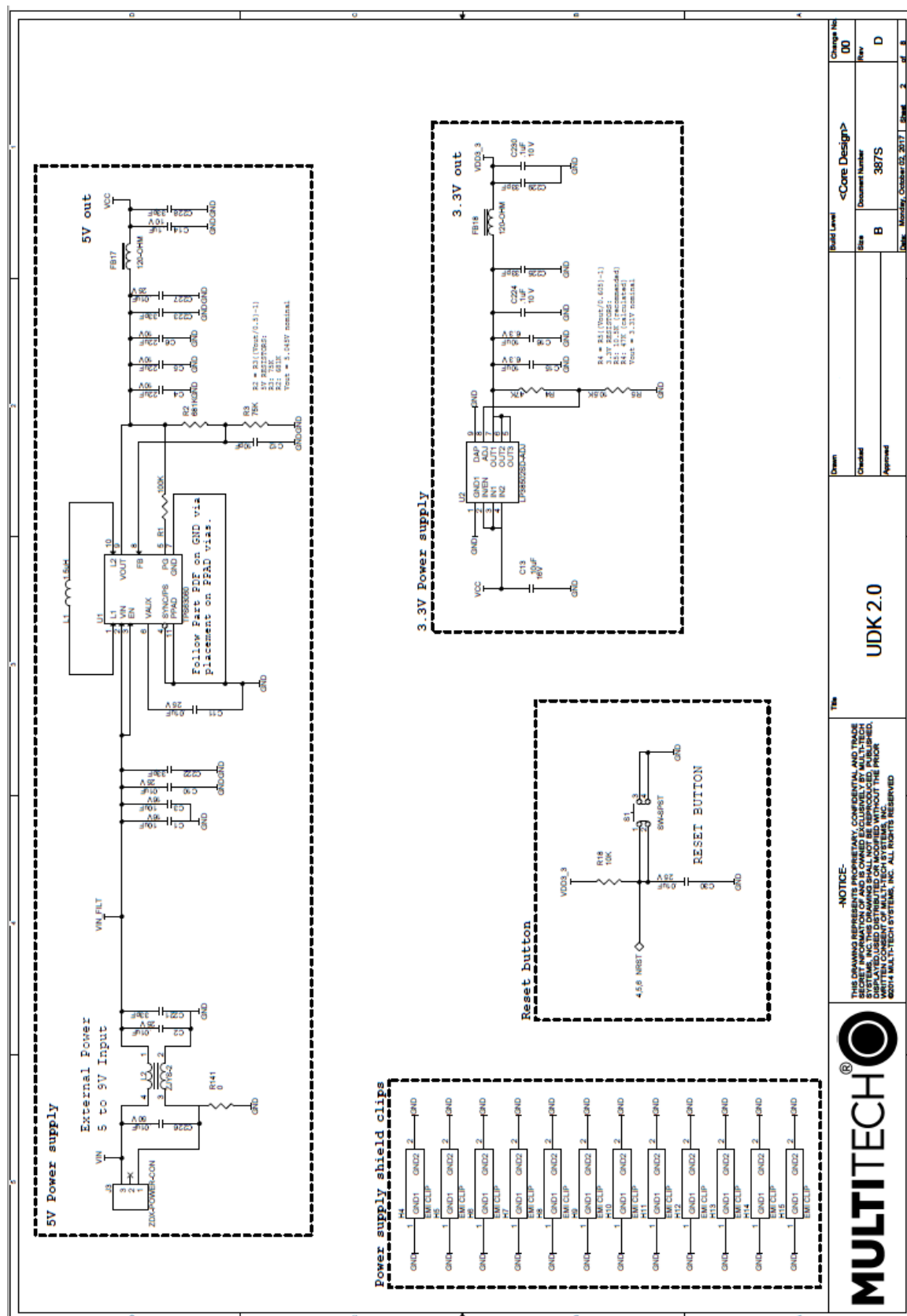




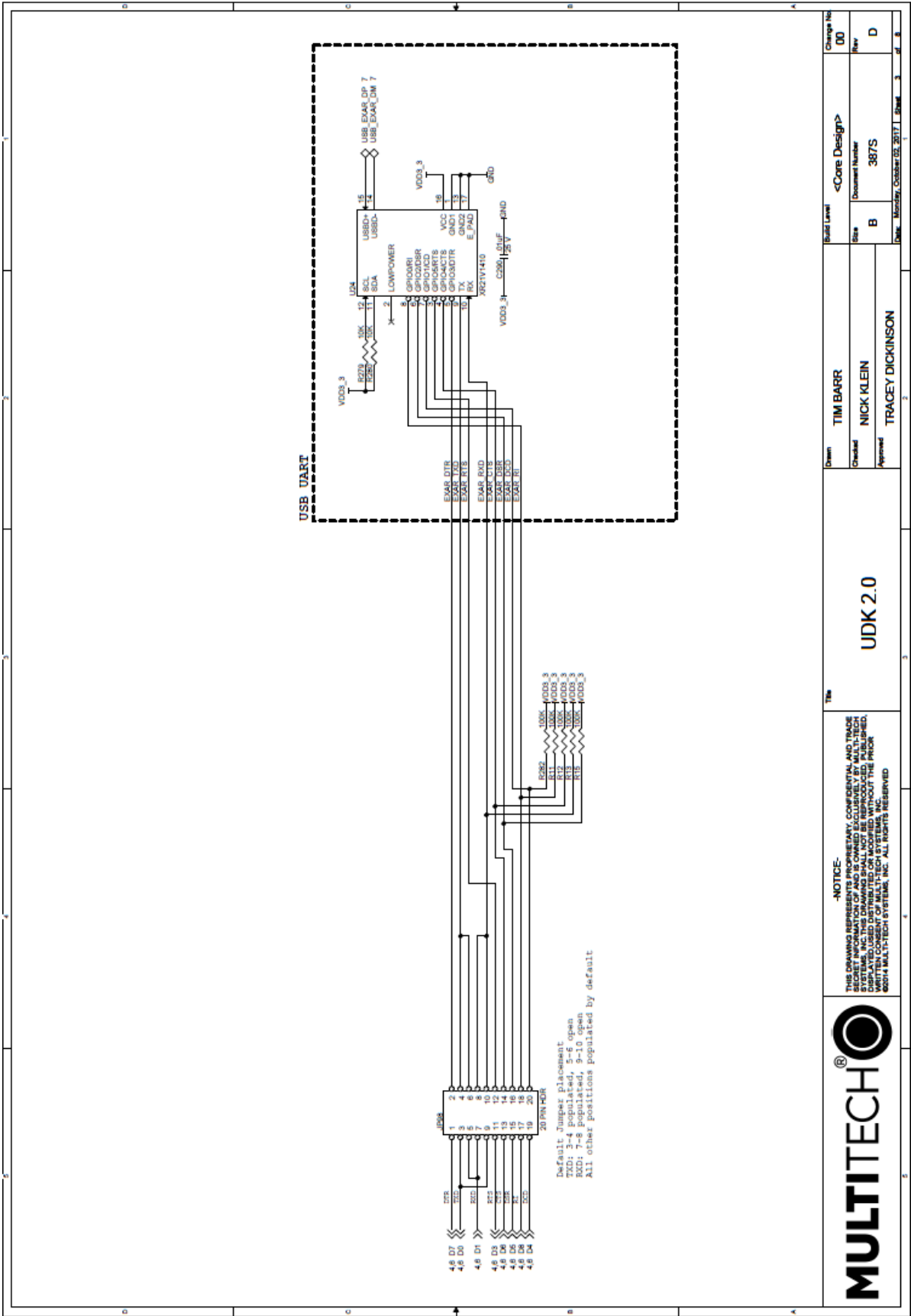
## Chapter 4 Block Diagram and Schematics

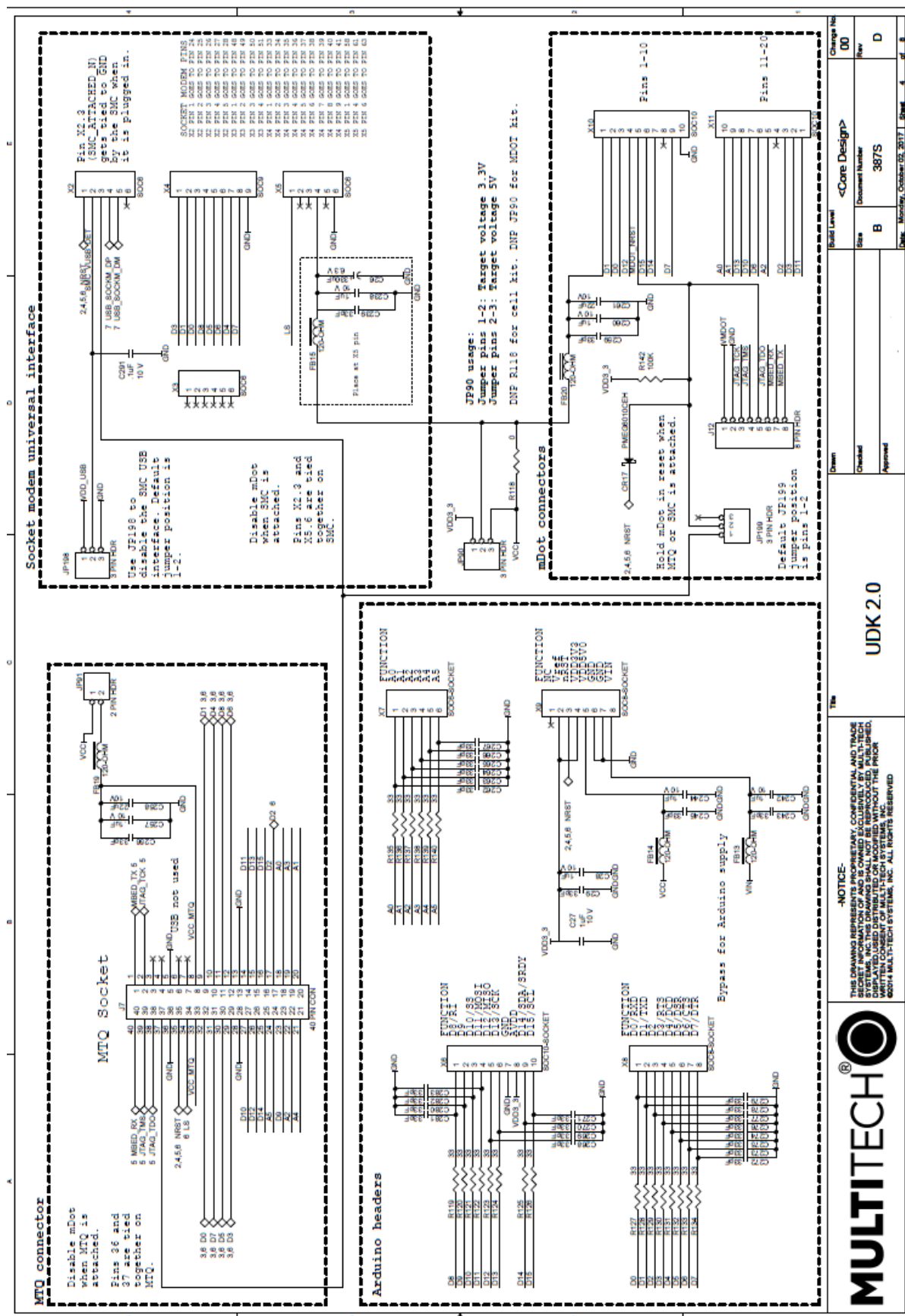
[illegible]

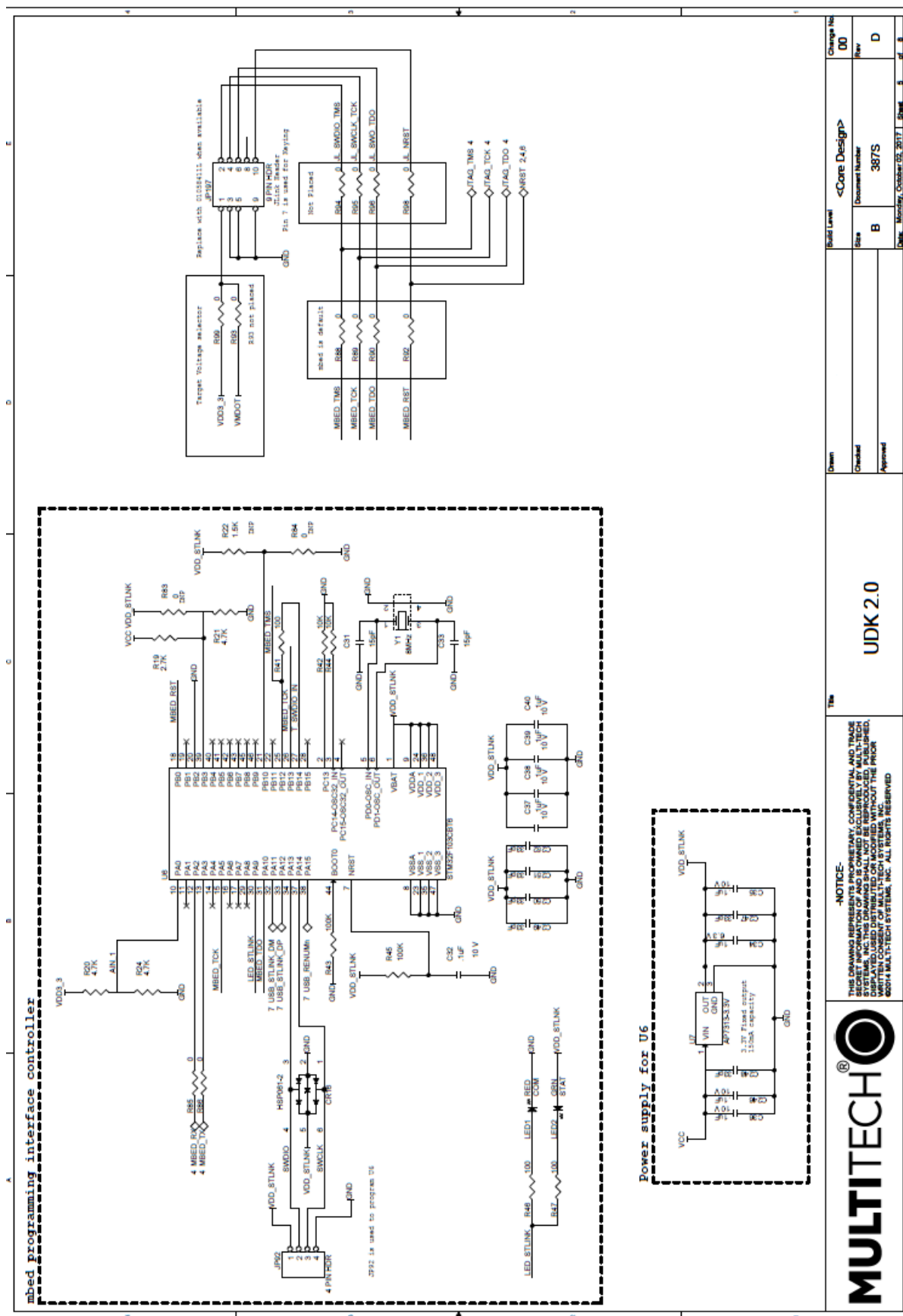
## Schematics

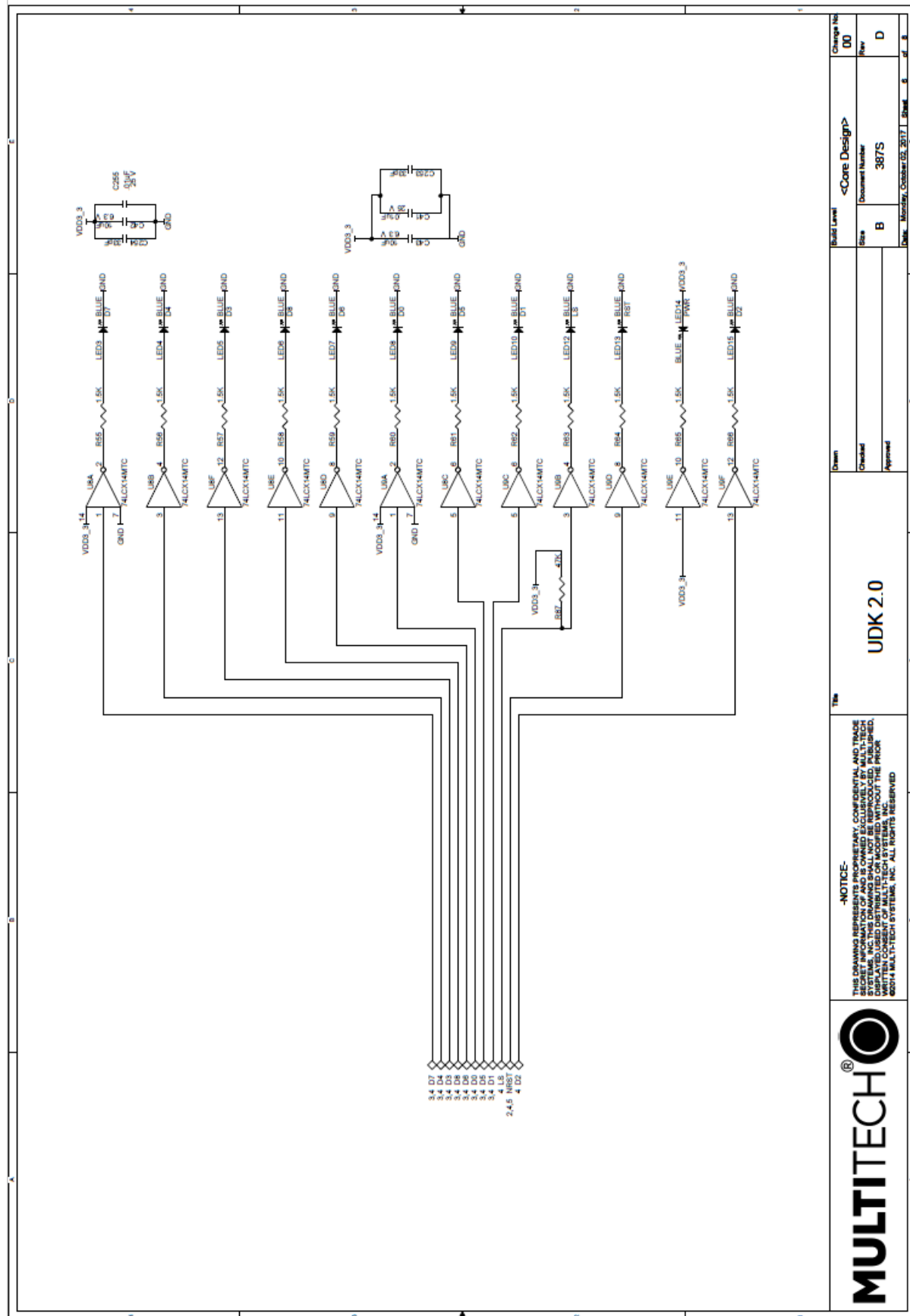


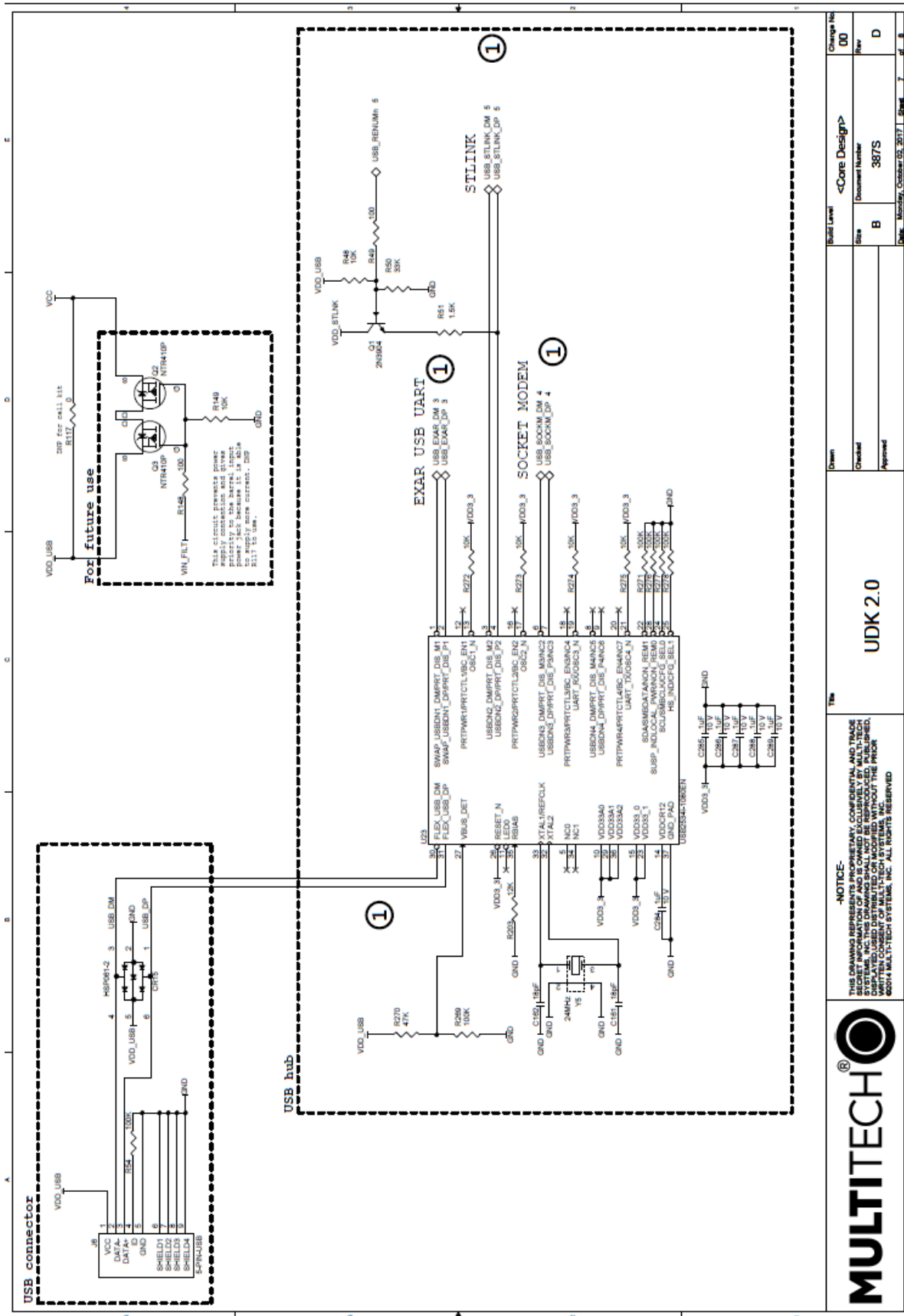














# Chapter 5 Design Considerations

## Noise Suppression Design

Adhere to engineering noise-suppression practices when designing a printed circuit board (PCB). Noise suppression is essential to the proper operation and performance of the device and surrounding equipment.

Any OEM board design must consider both on-board and off-board generated noise that can affect digital signal processing. Both on-board and off-board generated noise that is coupled on-board can affect interface signal levels and quality. Noise in frequency ranges that affect device performance is of particular concern.

On-board generated electromagnetic interference (EMI) noise that can be radiated or conducted off-board is equally important. This type of noise can affect the operation of surrounding equipment. Most local government agencies have certification requirements that must be met for use in specific environments.

Proper PC board layout (component placement, signal routing, trace thickness and geometry, and so on) component selection (composition, value, and tolerance), interface connections, and shielding are required for the board design to achieve desired device performance and to attain EMI certification.

Other aspects of proper noise-suppression engineering practices are beyond the scope of this guide. Consult noise suppression techniques described in technical publications and journals, electronics and electrical engineering text books, and component supplier application notes.

## PC Board Layout Guideline

In a 4-layer design, provide adequate ground plane covering the entire board. In 4-layer designs, power and ground are typically on the inner layers. Ensure that all power and ground traces are 0.05 inches wide.

The recommended hole size for the device pins is 0.036 in. +/-0.003 in. in diameter. Use spacers to hold the device vertically in place during the wave solder process.

## Electromagnetic Interference

The following guidelines are offered specifically to help minimize EMI generation. Some of these guidelines are the same as, or similar to, the general guidelines. To minimize the contribution of device-based design to EMI, you must understand the major sources of EMI and how to reduce them to acceptable levels.

- Keep traces carrying high frequency signals as short as possible.
- Provide a good ground plane or grid. In some cases, a multilayer board may be required with full layers for ground and power distribution.
- Decouple power from ground with decoupling capacitors as close to the device's power pins as possible.
- Eliminate ground loops, which are unexpected current return paths to the power source and ground.
- Locate high frequency circuits in a separate area to minimize capacitive coupling to other circuits.
- Locate cables and connectors to avoid coupling from high frequency circuits.
- Lay out the highest frequency signal traces next to the ground grid.
- If using a multilayer board design, make no cuts in the ground or power planes and be sure the ground plane covers all traces.
- Minimize the number of through-hole connections on traces carrying high frequency signals.

- Avoid right angle turns on high frequency traces. Forty-five degree corners are good; however, radius turns are better.
- On 2-layer boards with no ground grid, provide a shadow ground trace on the opposite side of the board to traces carrying high frequency signals. This will be effective as a high frequency ground return if it is three times the width of the signal traces.
- Distribute high frequency signals continuously on a single trace rather than several traces radiating from one point.

## Electrostatic Discharge Control

Handle all electronic devices with precautions to avoid damage due to the static charge accumulation.

See the ANSI/ESD Association Standard (ANSI/ESD S20.20-1999) – a document “for the Development of an Electrostatic Discharge Control for Protection of Electrical and Electronic Parts, Assemblies and Equipment.” This document covers ESD Control Program Administrative Requirements, ESD Training, ESD Control Program Plan Technical Requirements (grounding/bonding systems, personnel grooming, protected areas, packaging, marking, equipment, and handling), and Sensitivity Testing.

MultiTech strives to follow these recommendations. Input protection circuitry is incorporated in MultiTech devices to minimize the effect of static buildup. Take precautions to avoid exposure to electrostatic discharge during handling.

MultiTech uses and recommends that others use anti-static boxes that create a faraday cage (packaging designed to exclude electromagnetic fields). MultiTech recommends that you use our packaging when returning a product and when you ship your products to your customers.

## USB Design

MultiTech recommends that you review Intel's High Speed USB Platform Design Guidelines for information about USB signal routing, impedance, and layer stacking. Also:

- Shield USB cables with twisted pairs (especially those containing D+/D-).
- Use a single 5V power supply for USB devices. See Power Draw for current (ampere) requirements.
- Route D+/D- together in parallel with the trace spacing needed to achieve 90 ohms differential impedance for the USB pair and to maintain a 20 mil space from the USB pair and all other signals.
- If power is provided externally, use a common ground between the carrier board and the device.



## Warranty

To read the warranty statement for your product, visit <https://www.multitech.com/warranty>.

## Contact Information

General Information	<a href="mailto:info@multitech.com">info@multitech.com</a> <a href="https://multitech.com/contact-us/">https://multitech.com/contact-us/</a>
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Technical Support Portal	+1 (763) 717-5863 <a href="https://support.multitech.com">https://support.multitech.com</a>
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